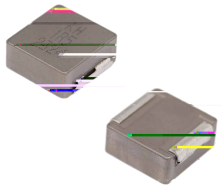
MDSA Series

SMD Low Profile High Current Molded Inductor

Size 1870



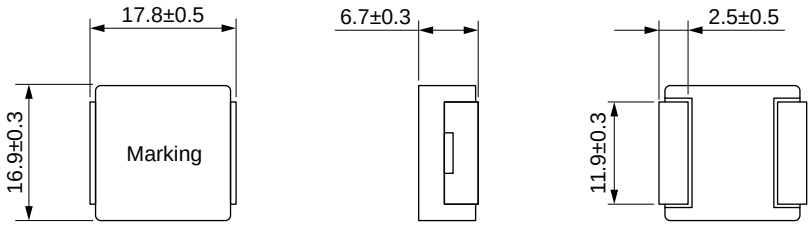
FEATURES

- S ł U t u
-
-
-
- Ultra low buzz noise, due to composite construc on.
-
- AEC-Q200 qualified
- Opera ng temperature: -55 to +155 °C(including self-temperature rise)
- Quan ty: 200PCS

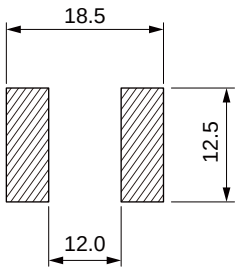
APPLICATION

- Noise filter for various drive circuitry requiring high temp. opera on and peak current handing capability
- Boost-Converter
- Buck-Converter DC/DC

Dimensions: [mm]



Land Pattern: [mm]



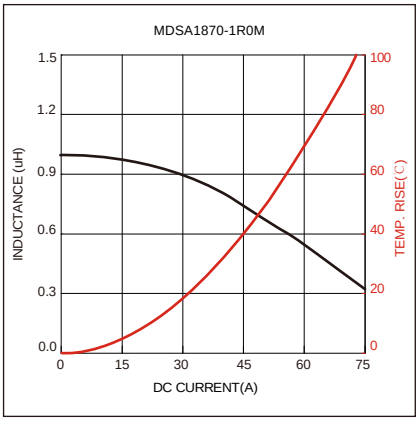
Electrical Properties:

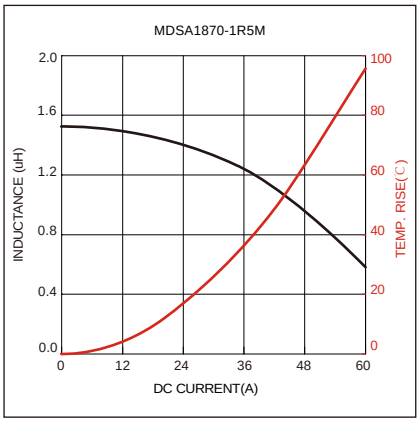
Part No		Tolerance	Temperature Rise Current Typ.	Temperature Rise Current Max.	Current Typ.	Current Max.	DC Resistance Typ.	DC Resistance Max.
				53.0			0.75	0.95
MDSA1870-R56M			56.0			67.5	0.85	
				40.5	50.0			1.35
						38.5	1.55	1.85
					35.0		1.85	2.25
							2.75	3.35
				25.0		25.0	3.75	4.55
					25.0			
				13.5		13.5		15.7

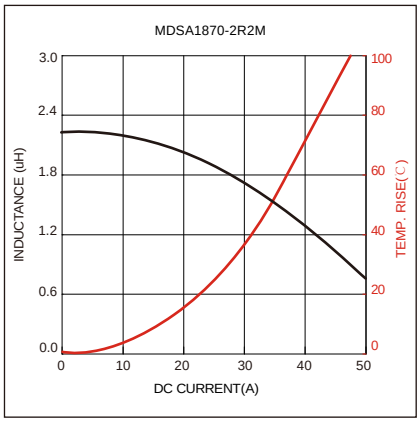
KOHER Electronics
F9, No. 4188, Huaning Rd, Minhang District, Shanghai
021-34753361 Contact@kohergroup.com

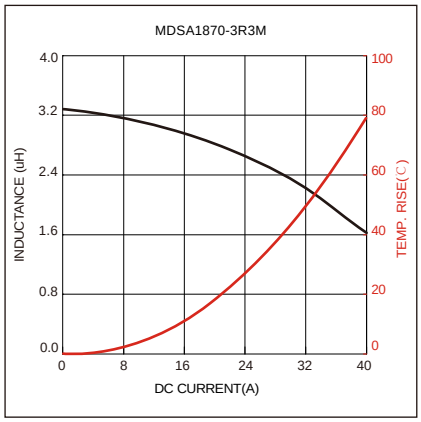
Temperion e Rio dt will : The actual value of DC c will cahen the temperion e rio dis

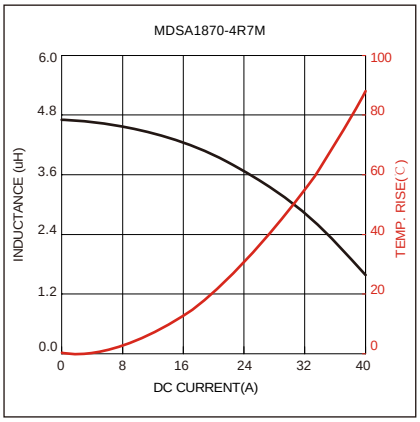
Typical Electrical Characteristics:

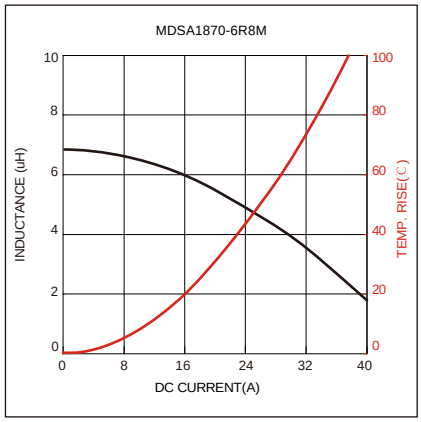


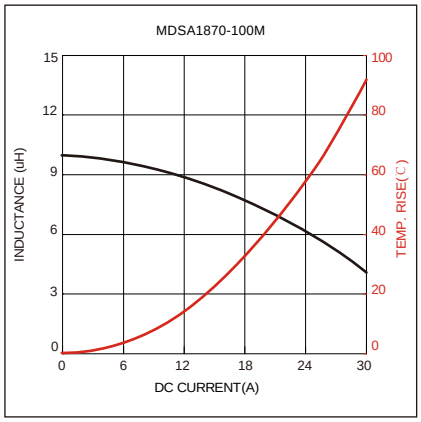


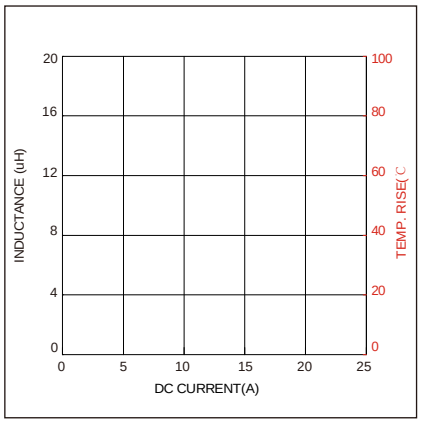




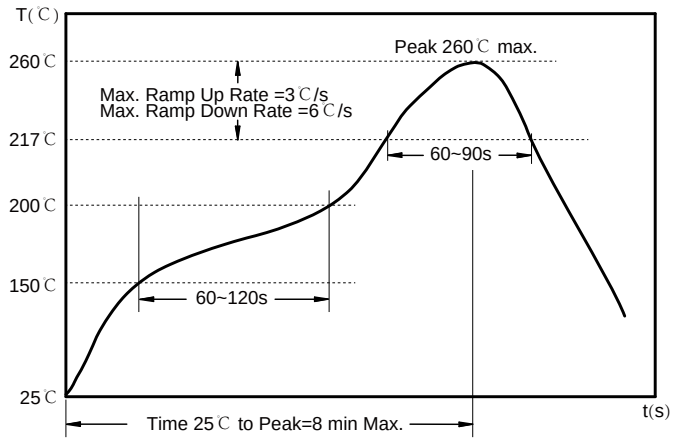







20
16
12
8
4
0
INDUCTANCE (uH)
100
80
60
40
20
0
TEMP. RISE(C
0
5
10
15
20
25
DC CURRENT(A)

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

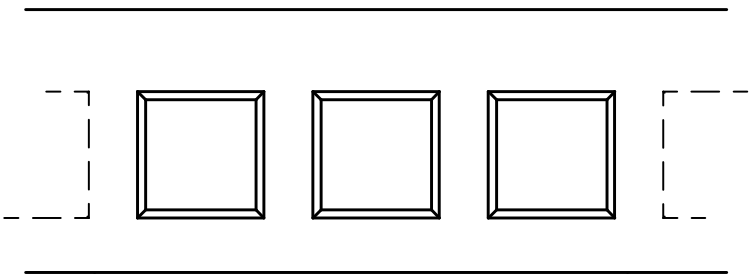
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

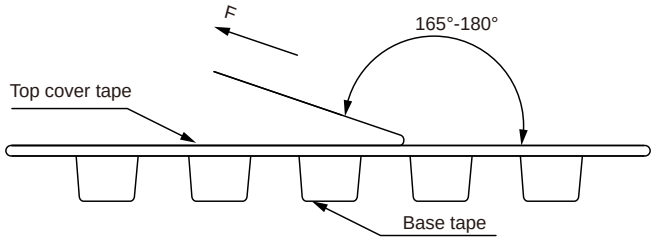
Packaging Information:

Tape Dimension:



A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
17.5±0.1	18.1±0.1	1.5±0.1	4.0±0.1	24.0±0.1	32.0±0.3	7.3±0.1	1.75±0.1	0.50±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	KH+Printing (Inductance+period)